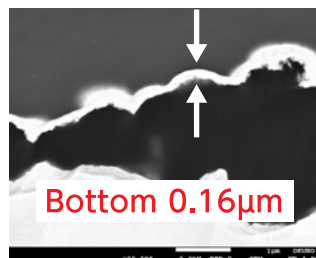
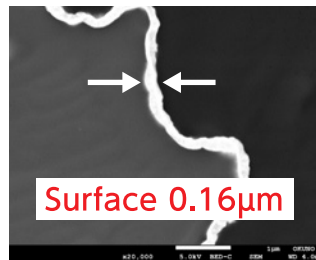
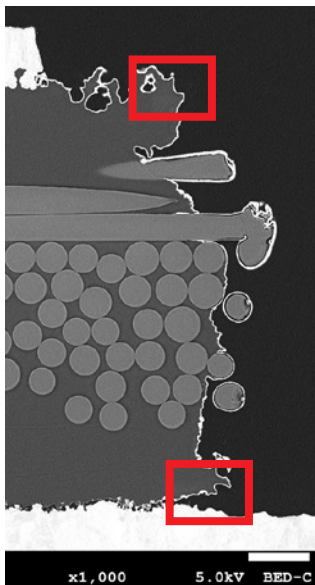


# OPC SUBLET PROCESS

Electroless copper plating process with high covering performance

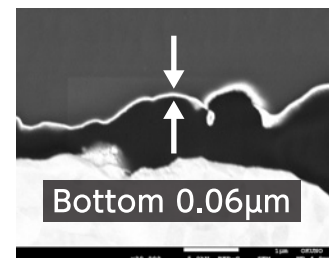
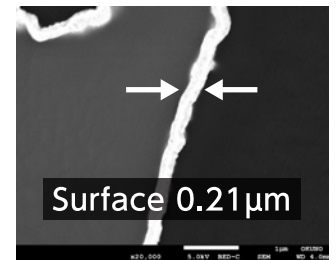
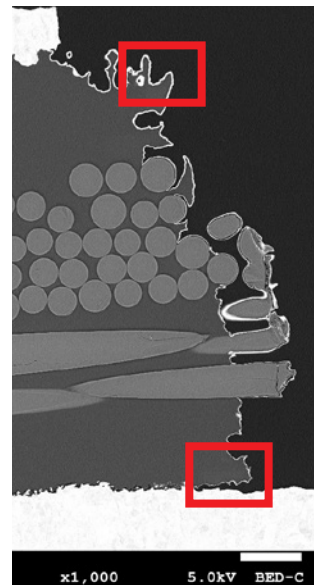
Excellent and uniform covering performance into holes

## OPC SUBLET PROCESS



TP 100%

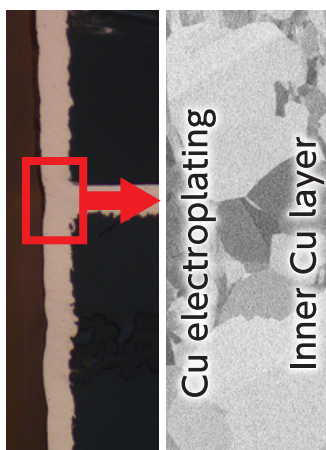
## Conventional



TP 29%

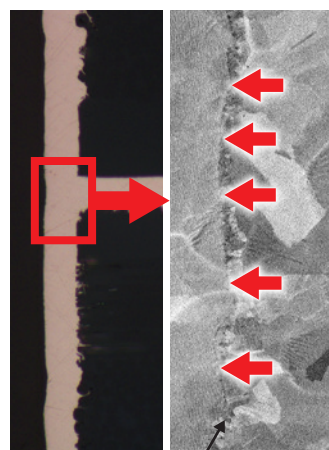
Improve connection reliability with inner Cu layer

## OPC SUBLET PROCESS



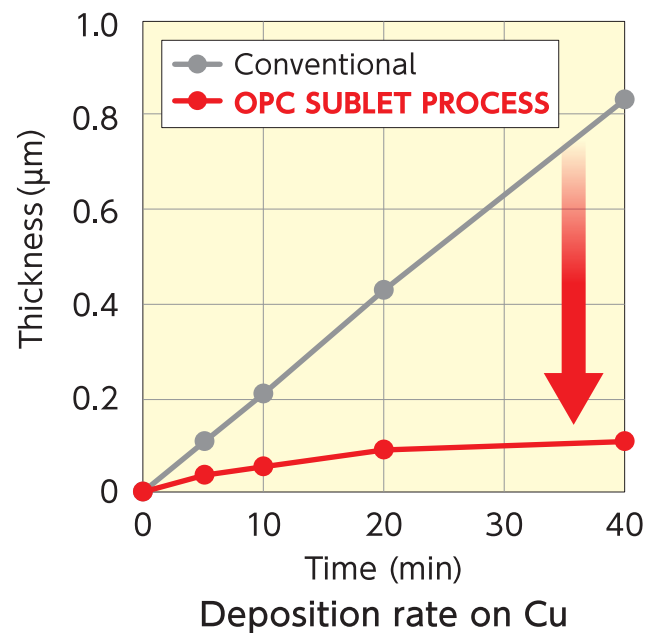
No interface

## Conventional



Interface  
(Electroless Cu plating)

No interface of inner copper foil and Cu films



Control Cu deposition